

Phys 475 - Design Review

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Table of Contents

- 1. Overview / Background
- 2. Specifications
- 3. Block Diagram
- 4. Detailed Schematics
- 5. Overview of Key Components
- 6. Current Issues / Roadblocks
- 7. GANTT chart for completing the project

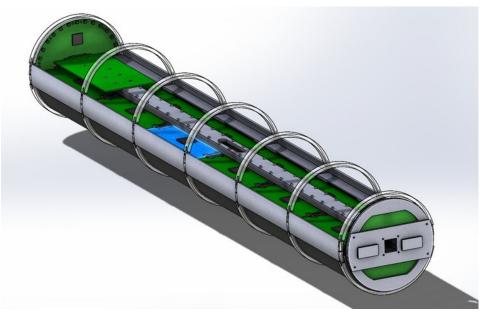


Figure 1. 3D model of Full BMD Detector

Overview / Background

- What
 - Design second version of muon detector using Multi-pixel Photon Counters (MPPC)
- Why
 - Tomographic reconstruction allows non invasive 3D imaging (e.g. CT scans, MRIs)
 - Muons have greater penetration, allowing deeper scanning than x-rays
 - 1st version was too large, thus there is a need to compress the system into 6" cylinder, approximately 1 meter long

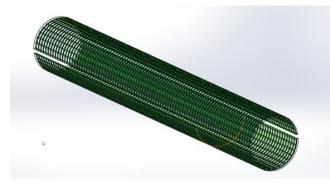


Figure 2. Cylindrical scintillator with light shifting fibers.

Overview / Background (continued)

• How

- Remove long CAT 6 cables to reduce signal noise and congestion
- Redesigning MPPC boards to include additional FPGA in order to have localized ASIC readout and initial data filtering
- Changed shape of scintillator from square rods to round hollow cylinder with light shifting fibers epoxied around and along cylinder

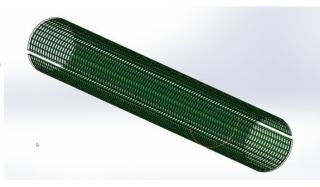


Figure 2. Cylindrical scintillator with light shifting fibers.

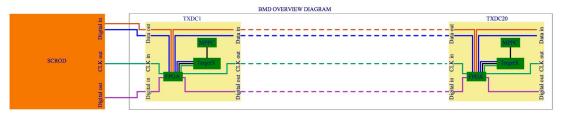
Project Objectives

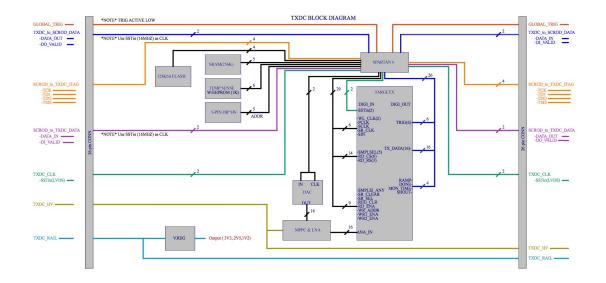
- 1. Design, fabricate, populate, and test the BMD daughter cards and interconnection board
- 2. Design, develop, integrate, and test firmware for subcomponents on daughter card
 - a. DAC
 - b. Temperature Sensor
 - c. SRAM
- 3. BMD control/configuration firmware
- 4. Data readout

Specifications

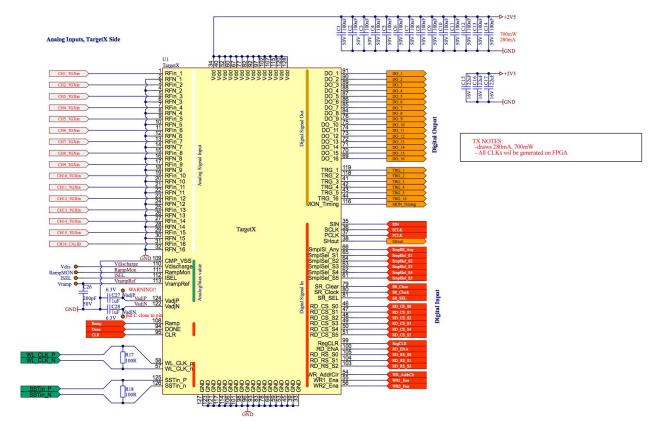
- Final BMD system will include
 - MPPC center daughter card
 - MPPC doughnut(end caps) daughter card
 - power board
 - SCROD
 - Cylindrical scintillator

Block Diagram



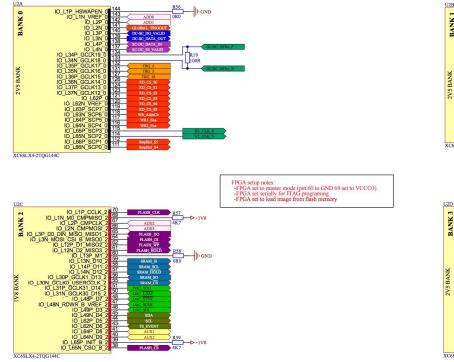


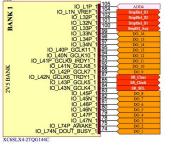
Detailed Schematics (TargetX)

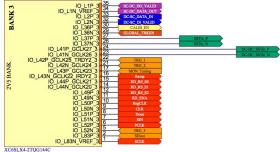


8

Detailed Schematics (FPGA)

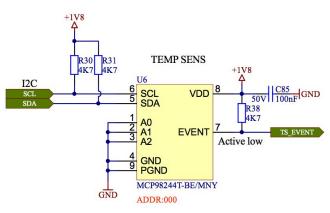


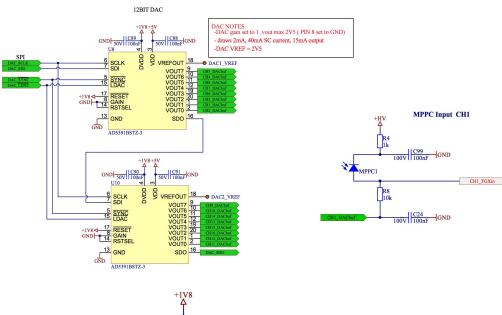


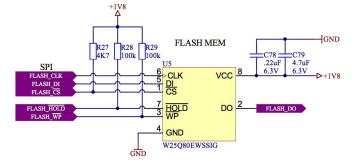


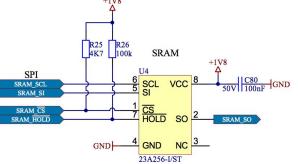
XC6SLX4-2TOG144C

Detailed Schematics









Overview of Key Components

- Hamamatsu S12572-050/P MPPCs, along with the scintillators, are used for capturing and tracing the muons.
- TargetX waveform sampling/digitizing ASIC is used for capturing, saving, and digitizing the muon events.

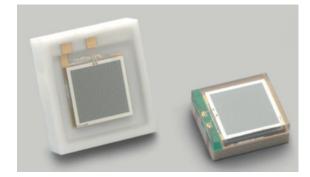


Figure 2. Hamamatsu S12572-050/PMPPC

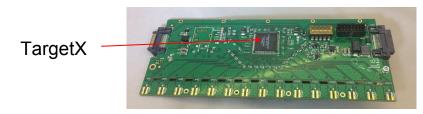


Figure 2. Daughter Card

Overview of Key Components (continued)

- Interface board
 - The purpose of the interface board is to connect Ο SCROD with the daughter cards.
- SCROD
 - SCROD card acts as a mother board. The 0 SPARTAN6 FPGA is used to control the daughter cards.

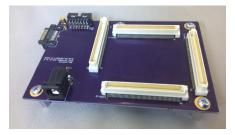


Figure 2. Interface Board



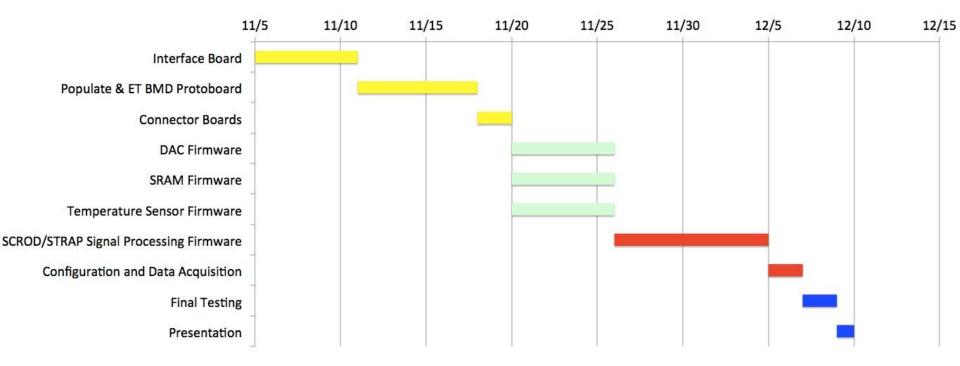
Figure 2. SCROD

SPARTAN 6 FPGA

Current Issues / Roadblocks

- Firmware for subcomponents cannot be tested until interconnection board and SCROD are integrated, allowing the clock to be fed from SCROD.
- Firmware and frontend for control, processing, and communications cannot be completed until existing SCROD/STRAP code is obtained for review.
- Full system cannot be tested until the mechanical components are complete.

GANTT chart



Conclusion

- The circuit boards are done
- Temperature sensor firmware is ready for integration
- DAC and SRAM firmwares are ongoing

Future Work

- SCROD/STRAP signal processing firmware
- Configuration and data taking software
- GUI display/running software
- Make a testing jig for the completed system



Figure 2. Testing Jig.

Questions?

(please say no)

(please clap)

